

Title (en)
COPPER ALLOY MATERIAL FOR ELECTRICAL AND ELECTRONIC COMPONENTS, AND MANUFACTURING METHOD THEREFOR

Title (de)
KUPFERLEGIERUNGSMATERIAL FÜR ELEKTRISCHE UND ELEKTRONISCHE BAUTEILE SOWIE HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)
MATERIAU EN ALLIAGE DE CUIVRE POUR COMPOSANTS ELECTRIQUES ET ELECTRONIQUES ET PROCEDE DE FABRICATION ASSOCIE

Publication
EP 2319947 A4 20111123 (EN)

Application
EP 09803032 A 20090730

Priority

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- JP 2008197672 A 20080731
- JP 2008197677 A 20080731
- JP 2008202468 A 20080805

Abstract (en)
[origin: EP2319947A1] A copper alloy material for an electric/electronic part, having a composition comprising Co 0.5 to 2.0 mass% and Si 0.1 to 0.5 mass%, with the balance of Cu and inevitable impurities, in which a copper alloy of a matrix has a grain size of 3 to 35 µm, a precipitate composed of Co and Si has a particle size of 5 to 50 nm, the precipitate has a density of 1×10^8 to 1×10^{10} number/mm², and the copper alloy material has a tensile strength of 550 MPa and an electrical conductivity of 50 %IACS or more.

IPC 8 full level
C22C 9/06 (2006.01); **C22C 9/00** (2006.01); **C22C 9/02** (2006.01); **C22C 9/04** (2006.01); **C22C 9/05** (2006.01); **C22C 9/10** (2006.01); **C22F 1/00** (2006.01); **C22F 1/08** (2006.01); **H01B 1/02** (2006.01); **H01B 13/00** (2006.01)

CPC (source: EP US)
C22C 9/06 (2013.01 - EP US); **C22C 9/10** (2013.01 - EP US); **C22F 1/00** (2013.01 - EP US); **C22F 1/08** (2013.01 - EP US); **H01B 1/023** (2013.01 - EP US)

Citation (search report)

- [I] US 2008056930 A1 20080306 - ITO TAKEFUMI [JP], et al
- [E] EP 2248921 A1 20101110 - FURUKAWA ELECTRIC CO LTD [JP]
- See references of WO 2010013790A1

Cited by
EP2778240A4; KR20140056003A; EP2728025A3; US9587299B2; US10153063B2; US9499885B2; US10458003B2; US10032536B2; US10056165B2

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DOCDB simple family (application)
EP 09803032 A 20090730; CN 200980130311 A 20090730; JP 2009063616 W 20090730; JP 2010507743 A 20090730; KR 20117003772 A 20090730; US 201113016260 A 20110128